

#### 1.MATERIAL:

MOLDING: LCP UL94 V-0

CONTACT: COPPER ALLOY.

GOLD PLATED Min ON CONTACT AREA, 100u"

Min TIN (LEAD FREE) ON SOLDER AREA,

SHELL: SUS304-H,T=0.30±0.03mm

50u" NICKEL PLATING OVER ALL.

MID PLATE: SUS301-H,T=0.15±0.03mm

Ni 30u" MIN. UNDER PLATED OVER ALL.

Sn 80u" MIN. PLATED OVER ALL

#### 2.MECHANICAL:

INSERTION: 5~20N.

EXTRACTION: 8~20N AFTER TEST.

DURABILITY: 10000 CYCLES

#### 3.ELECTRICAL:

CURRENT: 5A FOR VBUS;

1.25A FOR GND PIN.

0.25A FOR OTHER.

VOLTAGE: 20 V MAX

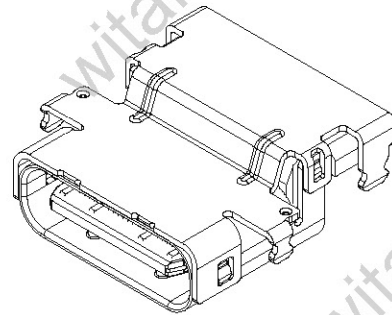
WITHSTANDING VOLTAGE: 100V AC R.M.S.

CONTACT RESISTANCE: 40mΩ MAX.

INSULATION RESISTANCE: 100MΩ MIN.

#### 4.ENVIRONMENTAL

TEMPERATURE RANGE -25°C ~ +85°C



PART NO.:  
SEE THE PART NUMBER CODE

GENERAL TOLERANCES (UNLESS SPECIFIED)	
X.XXXX	± ---
X.XXX	± 0.10
X.XX	± 0.25
X.X	± 0.30
ANGULAR	± --°

深圳市纬域科技有限公司  
SHENZHEN WITAREA TECHNOLOGY CO., LTD

TITLE USB 4.0 TYPE C 24PIN RECEPTACLE , MID-MOUNT OFFSET 2.93MM, DUAL-ROW SMT.WITH BRACKET, CH=1.4MM, L=9.92MM	
DWG.NO. W0028-24-MM1-S9	SHEET NO. 1 OF 2
DIMENSION STYLE MM ONLY	DESIGN UNITS METRIC
SCALE 1:1	

DRAWN BY ANDY YANG	DATE 2022.05.21
CHECKED BY JAMES XIAO	DATE 2022.05.21
APPROVED BY JASON ZENG	DATE 2022.05.21

THIRD ANGLE PROJECTION

Pin	Signal Name	Mating Sequence	Pin	Signal Name	Mating Sequence
A1	GND	First	B12	GND	First
A2	SSTXp1	Second	B11	SSRXp1	Second
A3	SSTXn1	Second	B10	SSRXn1	Second
A4	V <sub>bus</sub>	First	B9	V <sub>bus</sub>	First
A5	CC1	Second	B8	SBU2	Second
A6	Dp1	Second	B7	Dn2	Second
A7	Dn1	Second	B6	Dp2	Second
A8	SBU1	Second	B5	CC2	Second
A9	V <sub>bus</sub>	First	B4	V <sub>bus</sub>	First
A10	SSRXn2	Second	B3	SSTXn2	Second
A11	SSRXp2	Second	B2	SSTXp2	Second
A12	GND	First	B1	GND	First

frame size: A4